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Details

Product Status	Active
Core Processor	S12Z
Core Size	16-Bit
Speed	32MHz
Connectivity	I ² C, IrDA, LINbus, SCI, SPI, UART/USART
Peripherals	LVD, POR, PWM, WDT
Number of I/O	34
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	128 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	5.5V ~ 18V
Data Converters	A/D 10x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/s9s12zvl16f0clf

Appendix L MSCAN Electrical Specifications

L.1	MSCAN Wake-up Pulse Timing	732
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Appendix M Package Information

M.1	48 LQFP	733
M.2	32 LQFP	735
M.3	32 QFN, MC9S12ZVLS device only	737

Appendix N Ordering Information

Appendix O Detailed Register Address Map

O.1	0x0000–0x0003 Part ID	745
O.2	0x0010–0x001F S12ZINT	745
O.3	0x0070–0x00FF S12ZMMC	747
O.4	0x0100–0x017F S12ZDBG	747
O.5	0x0200–0x037F PIM	750
O.6	0x0380–0x039F FTMRZ	755
O.7	0x03C0–0x03CF SRAM_ECC_32D7P	757
O.8	0x0400–0x042F TIM1	758
O.9	0x0480–x04AF PWM0	759
O.10	0x0500–x052F PWM1	761
O.11	0x05C0–0x05FF TIM0	763
O.12	0x0600–0x063F ADC0	765
O.13	0x0680–0x0687 DAC	767
O.14	0x0690–0x0697 ACMP	768
O.15	0x06C0–0x06DF CPMU	768
O.16	0x06F0–0x06F7 BATS	771
O.17	0x0700–0x0707 SCIO	771
O.18	0x0710–0x0717 SCII	772
O.19	0x0780–0x0787 SPI0	773
O.20	0x07C0–0x07C7 IIC0	774
O.21	0x0800–0x083F CAN0	775
O.22	0x0980–0x0987 LINPHY0	776
O.23	0x0B40–0x0B47 PGA	776



This byte can be erased and programmed like any other Flash location. Two bits of this byte are used for security (SEC[1:0]). The contents of this byte are copied into the Flash security register (FSEC) during a reset sequence.

The meaning of the security bits SEC[1:0] is shown in Table 1-10. For security reasons, the state of device security is controlled by two bits. To put the device in unsecured mode, these bits must be programmed to SEC[1:0] = '10'. All other combinations put the device in a secured mode. The recommended value to put the device in secured state is the inverse of the unsecured state, i.e. SEC[1:0] = '01'.

Table 1-10. Security Bits

SEC[1:0]	Security State
00	1 (secured)
01	1 (secured)
10	0 (unsecured)
11	1 (secured)

NOTE

Please refer to the Flash block description for more security byte details.

1.11.3 Operation of the Secured Microcontroller

By securing the device, unauthorized access to the EEPROM and Flash memory contents is prevented. Secured operation has the following effects on the microcontroller:

1.11.3.1 Normal Single Chip Mode (NS)

- Background debug controller (BDC) operation is completely disabled.
- Execution of Flash and EEPROM commands is restricted (described in flash block description).

1.11.3.2 Special Single Chip Mode (SS)

- Background debug controller (BDC) commands are restricted
- Execution of Flash and EEPROM commands is restricted (described in flash block description).

In special single chip mode the device is in active BDM after reset. In special single chip mode on a secure device, only the BDC mass erase and BDC control and status register commands are possible. BDC access to memory mapped resources is disabled. The BDC can only be used to erase the EEPROM and Flash memory without giving access to their contents.

1.11.4 Unsecuring the Microcontroller

Unsecuring the microcontroller can be done using three different methods:

1. Backdoor key access
2. Reprogramming the security bits
3. Complete memory erase

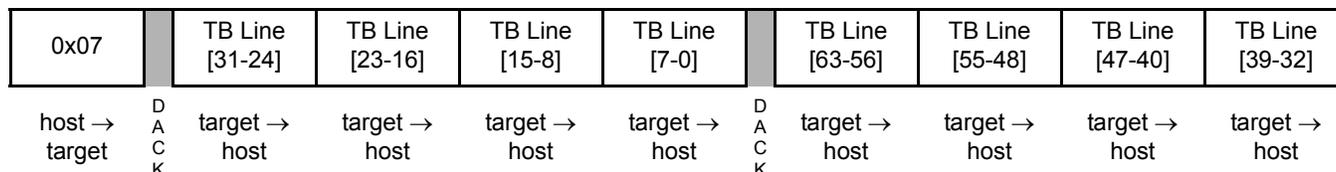
returned before the read data. This status byte reflects the state after the memory read was performed. If enabled, an ACK pulse is driven before the data bytes are transmitted.

The examples show the READ_MEM.B{_WS}, READ_MEM.W{_WS} and READ_MEM.L{_WS} commands.

5.4.4.12 READ_DBGTB

Read DBG trace buffer

Non-intrusive



This command is only available on devices, where the DBG module includes a trace buffer. Attempted use of this command on devices without a trace buffer return 0x00.

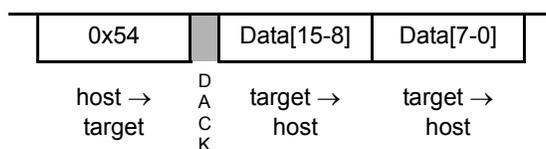
Read 64 bits from the DBG trace buffer. Refer to the DBG module description for more detailed information. If enabled an ACK pulse is generated before each 32-bit longword is ready to be read by the host. After issuing the first ACK a timeout is still possible whilst accessing the second 32-bit longword, since this requires separate internal accesses. The first 32-bit longword corresponds to trace buffer line bits[31:0]; the second to trace buffer line bits[63:32]. If ACK handshaking is disabled, the host must wait 16 clock cycles (DLY) after completing the first 32-bit read before starting the second 32-bit read.

5.4.4.13 READ_SAME.sz, READ_SAME.sz_WS

READ_SAME

Read same location specified by previous READ_MEM{_WS}

Non-intrusive



READ_SAME_WS

Read same location specified by previous READ_MEM{_WS}

Non-intrusive

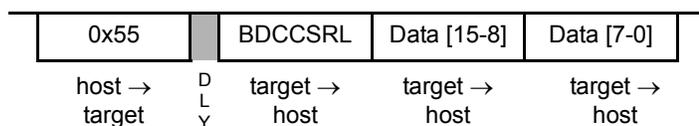


Table 7-15. SSF[2:0] — State Sequence Flag Bit Encoding

SSF[2:0]	Current State
000	State0 (disarmed)
001	State1
010	State2
011	State3
100	Final State
101,110,111	Reserved

7.3.2.8 Debug Comparator A Control Register (DBGACTL)

Address: 0x0110

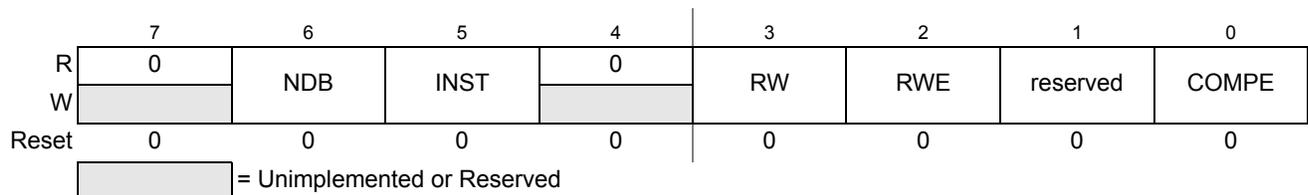


Figure 7-11. Debug Comparator A Control Register

Read: Anytime.

Write: If DBG not armed.

Table 7-16. DBGACTL Field Descriptions

Field	Description
6 NDB	Not Data Bus — The NDB bit controls whether the match occurs when the data bus matches the comparator register value or when the data bus differs from the register value. This bit is ignored if the INST bit in the same register is set. 0 Match on data bus equivalence to comparator register contents 1 Match on data bus difference to comparator register contents
5 INST	Instruction Select — This bit configures the comparator to compare PC or data access addresses. 0 Comparator compares addresses of data accesses 1 Comparator compares PC address
3 RW	Read/Write Comparator Value Bit — The RW bit controls whether read or write is used in compare for the associated comparator. The RW bit is ignored if RWE is clear or INST is set. 0 Write cycle is matched 1 Read cycle is matched
2 RWE	Read/Write Enable Bit — The RWE bit controls whether read or write comparison is enabled for the associated comparator. This bit is ignored when INST is set. 0 Read/Write is not used in comparison 1 Read/Write is used in comparison
0 COMPE	Enable Bit — Determines if comparator is enabled 0 The comparator is not enabled 1 The comparator is enabled

8.2.2.4 ECC Debug Pointer Register (ECCDPTRH, ECCDPTRM, ECCDPTRL)

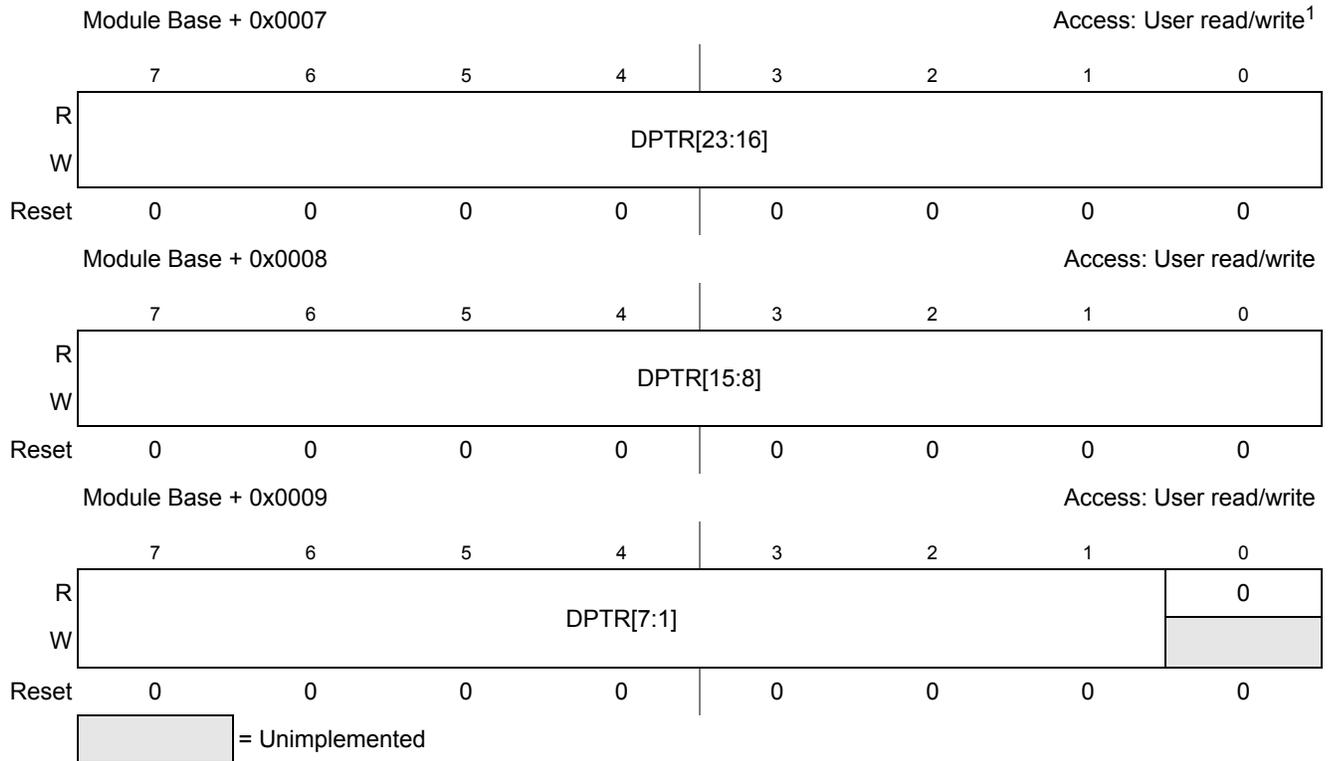


Figure 8-5. ECC Debug Pointer Register (ECCDPTRH, ECCDPTRM, ECCDPTRL)

¹ Read: Anytime
Write: Anytime

Table 8-5. ECCDPTR Register Field Descriptions

Field	Description
DPTR [23:0]	ECC Debug Pointer — This register contains the system memory address which will be used for a debug access. Address bits not relevant for SRAM address space are not writeable, so the software should read back the pointer value to make sure the register contains the intended memory address. It is possible to write an address value to this register which points outside the system memory. There is no additional monitoring of the register content; therefore, the software must make sure that the address value points to the system memory space.

Figure 9-2 shows a block diagram of the XOSCLCP.

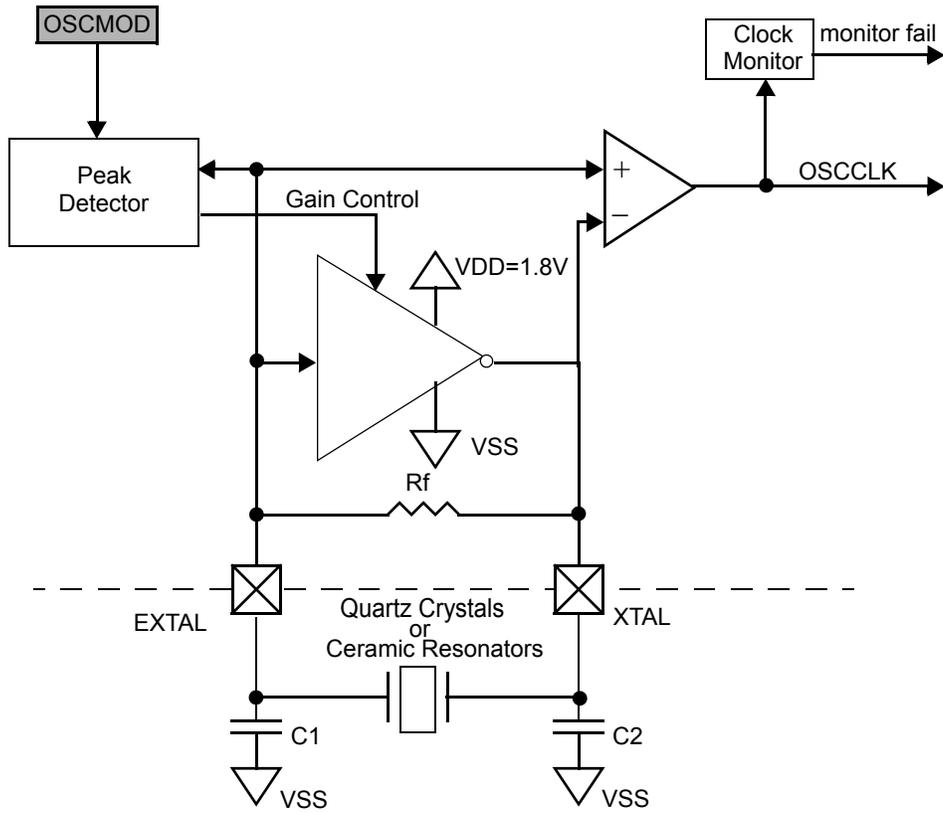


Figure 9-2. XOSCLCP Block Diagram

This supply domain is monitored by the Low Voltage Reset circuit.

VDDX has to be connected externally to VDDA.

9.2.6 BCTL — Base Control Pin for external PNP

BCTL is the ballast connection for the on chip voltage regulator. It provides the base current of an external BJT (PNP) of the VDDX and VDDA supplies. An additional 1K Ω resistor between emitter and base of the BJT is required. See the device specification if this pin is available on this device.

9.2.7 VSS — Core Logic Ground Pin

VSS is the core logic supply return pin. It must be grounded.

9.2.8 VDD — Internal Regulator Output Supply (Core Logic)

Node VDD is a device internal supply output of the voltage regulator that provides the power supply for the internal core logic.

This supply domain is monitored by the Low Voltage Reset circuit and The Power On Reset circuit.

9.2.9 VDDF — Internal Regulator Output Supply (NVM Logic)

Node VDDF is a device internal supply output of the voltage regulator that provides the power supply for the NVM logic.

This supply domain is monitored by the Low Voltage Reset circuit.

9.2.10 API_EXTCLK — API external clock output pin

This pin provides the signal selected via APIES and is enabled with APIEA bit. See the device specification if this clock output is available on this device and to which pin it might be connected.

9.2.11 TEMPSENSE — Internal Temperature Sensor Output Voltage

Depending on the VSEL setting either the voltage level generated by the temperature sensor or the VREG bandgap voltage is driven to a special channel input of the ADC Converter. See device level specification for connectivity of ADC special channels.

10.5.2.19 ADC Command Index Register (ADCCIDX)

It is important to note that these bits do not represent absolute addresses instead it is a sample index (object size 32bit).

Module Base + 0x001C

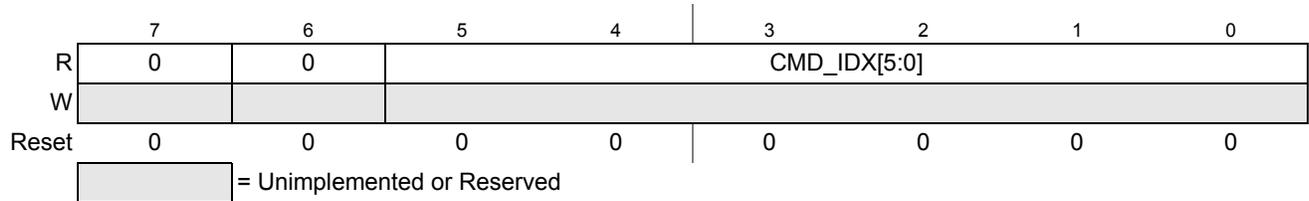


Figure 10-22. ADC Command Index Register (ADCCIDX)

Read: Anytime

Write: NA

Table 10-27. ADCCIDX Field Descriptions

Field	Description
5-0 CMD_IDX [5:0]	ADC Command Index Bits — These bits represent the command index value for the conversion commands relative to the two CSL start addresses in the memory map. These bits do not represent absolute addresses instead it is a sample index (object size 32bit). See also Section 10.6.3.2.2, "Introduction of the two Command Sequence Lists (CSLs)" for more details.

Please note that there is always a pump phase of two ADC_CLK cycles before the sample phase begins, hence glitches during the pump phase could impact the conversion accuracy for short sample times.

10.6.3 Digital Sub-Block

The digital sub-block contains a list-based programmer's model and the control logic for the analog sub-block circuits.

10.6.3.1 Analog-to-Digital (A/D) Machine

The A/D machine performs the analog-to-digital conversion. The resolution is program selectable to be either 8- or 10- or 12 bits. The A/D machine uses a successive approximation architecture. It functions by comparing the sampled and stored analog voltage with a series of binary coded discrete voltages.

By following a binary search algorithm, the A/D machine identifies the discrete voltage that is nearest to the sampled and stored voltage.

Only analog input signals within the potential range of VRL_0/1 to VRH_0/1/3 (availability of VRL_1 and VRH_2 see [Table 10-2](#)) (A/D reference potentials) will result in a non-railed digital output code.

10.6.3.2 Introduction of the Programmer's Model

The ADC_LBA provides a programmer's model that uses a system memory list-based architecture for definition of the conversion command sequence and conversion result handling.

The Command Sequence List (CSL) and Result Value List (RVL) are implemented in double buffered manner and the buffer mode is user selectable for each list (bits CSL_BMOD, RVL_BMOD). The 32-bit wide conversion command is double buffered and the currently active command is visible in the ADC register map at ADCCMD register space.

Table 13-12. CANRIER Register Field Descriptions

Field	Description
7 WUPIE ¹	Wake-Up Interrupt Enable 0 No interrupt request is generated from this event. 1 A wake-up event causes a Wake-Up interrupt request.
6 CSCIE	CAN Status Change Interrupt Enable 0 No interrupt request is generated from this event. 1 A CAN Status Change event causes an error interrupt request.
5-4 RSTATE[1:0]	Receiver Status Change Enable — These RSTAT enable bits control the sensitivity level in which receiver state changes are causing CSCIF interrupts. Independent of the chosen sensitivity level the RSTAT flags continue to indicate the actual receiver state and are only updated if no CSCIF interrupt is pending. 00 Do not generate any CSCIF interrupt caused by receiver state changes. 01 Generate CSCIF interrupt only if the receiver enters or leaves “bus-off” state. Discard other receiver state changes for generating CSCIF interrupt. 10 Generate CSCIF interrupt only if the receiver enters or leaves “RxErr” or “bus-off” ² state. Discard other receiver state changes for generating CSCIF interrupt. 11 Generate CSCIF interrupt on all state changes.
3-2 TSTATE[1:0]	Transmitter Status Change Enable — These TSTAT enable bits control the sensitivity level in which transmitter state changes are causing CSCIF interrupts. Independent of the chosen sensitivity level, the TSTAT flags continue to indicate the actual transmitter state and are only updated if no CSCIF interrupt is pending. 00 Do not generate any CSCIF interrupt caused by transmitter state changes. 01 Generate CSCIF interrupt only if the transmitter enters or leaves “bus-off” state. Discard other transmitter state changes for generating CSCIF interrupt. 10 Generate CSCIF interrupt only if the transmitter enters or leaves “TxErr” or “bus-off” state. Discard other transmitter state changes for generating CSCIF interrupt. 11 Generate CSCIF interrupt on all state changes.
1 OVRIE	Overrun Interrupt Enable 0 No interrupt request is generated from this event. 1 An overrun event causes an error interrupt request.
0 RXFIE	Receiver Full Interrupt Enable 0 No interrupt request is generated from this event. 1 A receive buffer full (successful message reception) event causes a receiver interrupt request.

¹ WUPIE and WUPE (see [Section 13.3.2.1, “MSCAN Control Register 0 \(CANCTL0\)”](#)) must both be enabled if the recovery mechanism from stop or wait is required.

² Bus-off state is only defined for transmitters by the CAN standard (see Bosch CAN 2.0A/B protocol specification). Because the only possible state change for the transmitter from bus-off to TxOK also forces the receiver to skip its current state to RxOK, the coding of the RXSTAT[1:0] flags define an additional bus-off state for the receiver (see [Section 13.3.2.5, “MSCAN Receiver Flag Register \(CANRFLG\)”](#)).

13.3.2.7 MSCAN Transmitter Flag Register (CANTFLG)

The transmit buffer empty flags each have an associated interrupt enable bit in the CANTIER register.

14.3.2.1 BATS Module Enable Register (BATE)

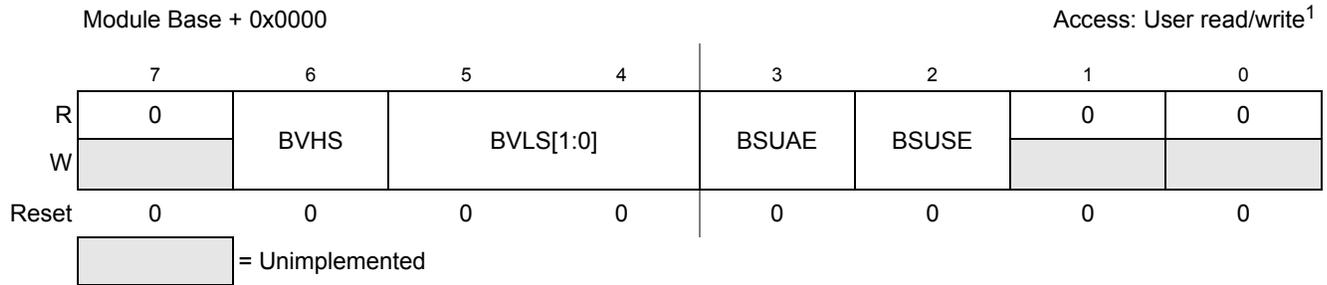


Figure 14-3. BATS Module Enable Register (BATE)

¹ Read: Anytime
Write: Anytime

Table 14-2. BATE Field Description

Field	Description
6 BVHS	BATS Voltage High Select — This bit selects the trigger level for the Voltage Level High Condition (BVHC). 0 Voltage level V_{HBI1} is selected 1 Voltage level V_{HBI2} is selected
5:4 BVLS[1:0]	BATS Voltage Low Select — This bit selects the trigger level for the Voltage Level Low Condition (BVLC). 00 Voltage level V_{LBI1} is selected 01 Voltage level V_{LBI2} is selected 10 Voltage level V_{LBI3} is selected 11 Voltage level V_{LBI4} is selected
3 BSUAE	BATS VSUP ADC Connection Enable — This bit connects the VSUP pin through the resistor chain to ground and connects the ADC channel to the divided down voltage. 0 ADC Channel is disconnected 1 ADC Channel is connected
2 BSUSE	BATSV3 VSUP Level Sense Enable — This bit connects the VSUP pin through the resistor chain to ground and enables the Voltage Level Sense features measuring BVLC and BVHC. 0 Level Sense features disabled 1 Level Sense features enabled

NOTE

When opening the resistors path to ground by changing BSUSE or BSUAE then for a time T_{EN_UNC} + two bus cycles the measured value is invalid. This is to let internal nodes be charged to correct value. BVHIE, BVLIE might be cleared for this time period to avoid false interrupts.

Register Name		Bit 7	6	5	4	3	2	1	Bit 0
0x0009 TCTL2	R W	RESERVED	RESERVED	RESERVED	RESERVED	OM1	OL1	OM0	OL0
0x000A TCTL3	R W	RESERVED							
0x000B TCTL4	R W	RESERVED	RESERVED	RESERVED	RESERVED	EDG1B	EDG1A	EDG0B	EDG0A
0x000C TIE	R W	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	C1I	C0I
0x000D TSCR2	R W	TOI	0	0	0	RESERVED	PR2	PR1	PR0
0x000E TFLG1	R W	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	C1F	C0F
0x000F TFLG2	R W	TOF	0	0	0	0	0	0	0
0x0010–0x001F TCxH–TCxL ¹	R W	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8
	R W	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
0x0024–0x002B Reserved	R W								
0x002C OCPD	R W	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	OCPD1	OCPD0
0x002D Reserved	R								
0x002E PTPSR	R W	PTPS7	PTPS6	PTPS5	PTPS4	PTPS3	PTPS2	PTPS1	PTPS0
0x002F Reserved	R W								

Figure 16-3. TIM16B2CV3 Register Summary (Sheet 2 of 2)

¹ The register is available only if corresponding channel exists.

16.3.2.1 Timer Input Capture/Output Compare Select (TIOS)

Module Base + 0x0000

	7	6	5	4	3	2	1	0
R	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	IOS1	IOS0
W	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	IOS1	IOS0
Reset	0	0	0	0	0	0	0	0

Figure 16-4. Timer Input Capture/Output Compare Select (TIOS)

Read: Anytime

Write: Anytime

Register Name		Bit 7	6	5	4	3	2	1	Bit 0
0x0006 SCIDRH	R	R8	T8	0	0	0	Reserved	Reserved	Reserved
	W								
0x0007 SCIDRL	R	R7	R6	R5	R4	R3	R2	R1	R0
	W	T7	T6	T5	T4	T3	T2	T1	T0

1. These registers are accessible if the AMAP bit in the SCISR2 register is set to zero.

2. These registers are accessible if the AMAP bit in the SCISR2 register is set to one.

 = Unimplemented or Reserved

Figure 18-2. SCI Register Summary (Sheet 2 of 2)

18.3.2.1 SCI Baud Rate Registers (SCIBDH, SCIBDL)

Module Base + 0x0000

	7	6	5	4	3	2	1	0
R	SBR15	SBR14	SBR13	SBR12	SBR11	SBR10	SBR9	SBR8
W								
Reset	0	0	0	0	0	0	0	0

Figure 18-3. SCI Baud Rate Register (SCIBDH)

Module Base + 0x0001

	7	6	5	4	3	2	1	0
R	SBR7	SBR6	SBR5	SBR4	SBR3	SBR2	SBR1	SBR0
W								
Reset	0	1	0	0	0	0	0	0

Figure 18-4. SCI Baud Rate Register (SCIBDL)

Read: Anytime, if AMAP = 0.

Write: Anytime, if AMAP = 0.

NOTE

Those two registers are only visible in the memory map if AMAP = 0 (reset condition).

The SCI baud rate register is used by to determine the baud rate of the SCI, and to control the infrared modulation/demodulation submodule.

Chapter 21

LIN Physical Layer (S12LINPHYV2)

Table 21-1. Revision History Table

Rev. No. (Item No.)	Date (Submitted By)	Sections Affected	Substantial Change(s)
V02.11	19 Sep 2013	All	- Removed preliminary note. - Fixed grammar and spelling throughout the document.
V02.12	20 Sep 2013	Standby Mode	- Clarified Standby mode behavior.
V02.13	8 Oct 2013	All	- More grammar, spelling, and formatting fixes throughout the document.

21.1 Introduction

The LIN (Local Interconnect Network) bus pin provides a physical layer for single-wire communication in automotive applications. The LIN Physical Layer is designed to meet the LIN Physical Layer 2.2 specification from LIN consortium.

21.1.1 Features

The LIN Physical Layer module includes the following distinctive features:

- Compliant with LIN Physical Layer 2.2 specification.
- Compliant with the SAE J2602-2 LIN standard.
- Standby mode with glitch-filtered wake-up.
- Slew rate selection optimized for the baud rates: 10.4 kbit/s, 20 kbit/s and Fast Mode (up to 250 kbit/s).
- Switchable 34 k Ω /330 k Ω pullup resistors (in shutdown mode, 330 k Ω only)
- Current limitation for LIN Bus pin falling edge.
- Overcurrent protection.
- LIN TxD-dominant timeout feature monitoring the LPTxD signal.
- Automatic transmitter shutdown in case of an overcurrent or TxD-dominant timeout.
- Fulfills the OEM “Hardware Requirements for LIN (CAN and FlexRay) Interfaces in Automotive Applications” v1.3.

The LIN transmitter is a low-side MOSFET with current limitation and overcurrent transmitter shutdown. A selectable internal pullup resistor with a serial diode structure is integrated, so no external pullup components are required for the application in a slave node. To be used as a master node, an external

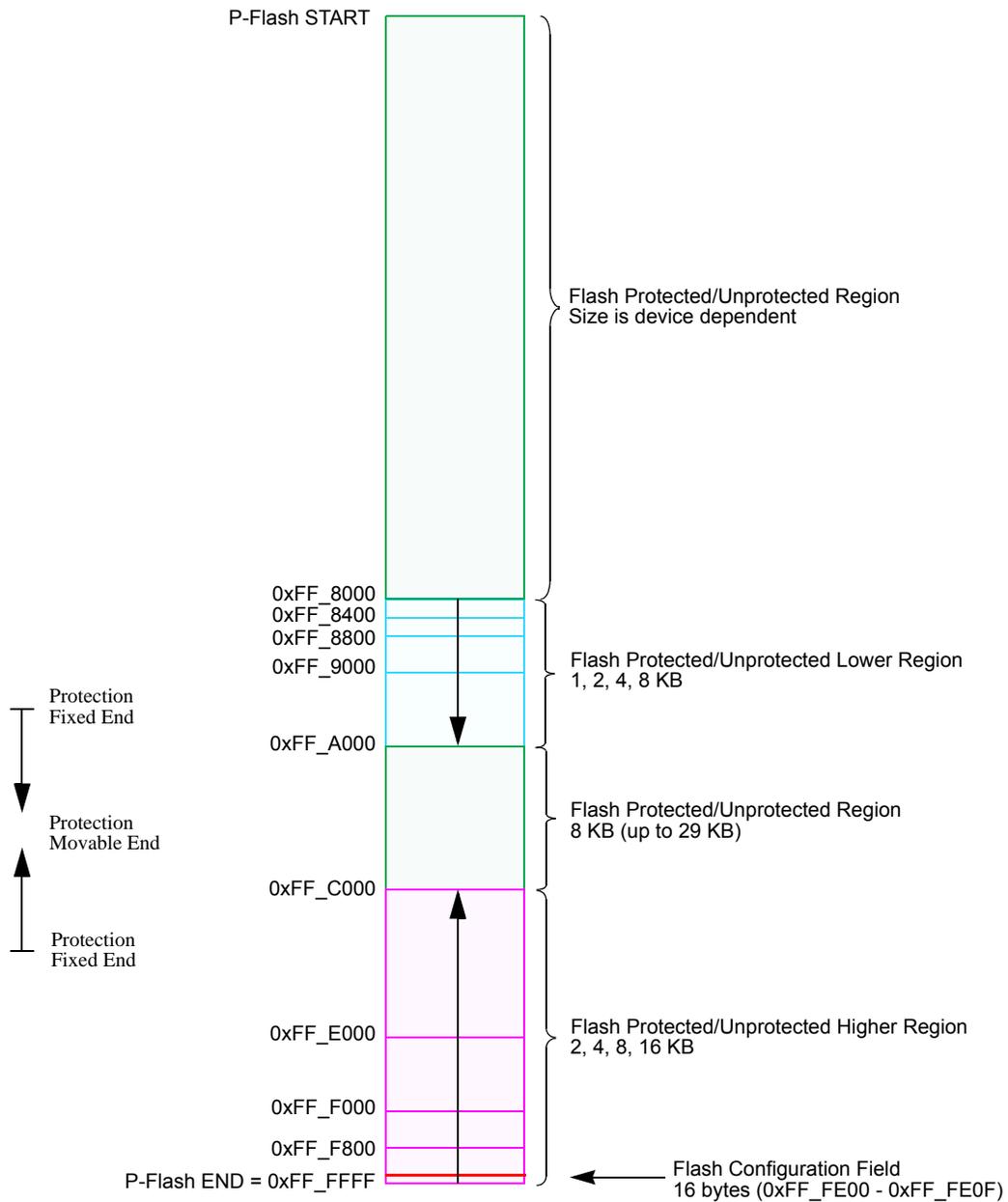


Figure 22-2. P-Flash Memory Map With Protection Alignment

Table A-1. Revision History Table

Revision Number	Revision Date	Description Of Changes
0.50	14 March 2016	<ul style="list-style-type: none"> added the latest characterization data, updated: Table A-11, Table A-19 change voltage specification for MC9S12ZVL128/96/64 analog modules to $V_{DDX} \pm 3\%$:
0.60	31 March 2016	<ul style="list-style-type: none"> update V_{BG} output voltage and V_{BG} voltage distribution specification: Table B-1
0.70	18 April 2016	<ul style="list-style-type: none"> correct min V_{DDX} specification for MC9S12ZVL128/96/64 device: Table B-1
0.80	20 June 2016	<ul style="list-style-type: none"> update Table A-19, add missing stop current for 85°C and 105°C, correct stop value for 125°C update Table I-2, set ACMP input offset to 25mV
0.90	08 August 2017	<ul style="list-style-type: none"> added 175°C parameters update current injection consideration, section Section C.1.1.4 Current Injection
1.0	12 September 2017	<ul style="list-style-type: none"> added 175°C Run and Wait current parameters
1.1	10 October 2017	<ul style="list-style-type: none"> added Pin input leakage values for Pins PAD0 and PAD1 at $150^\circ\text{C} < T_J < 175^\circ\text{C}$, Table A-10 added Pin input leakage values for Pins PP1, PP3, PP5 and PP7 at $150^\circ\text{C} < T_J < 175^\circ\text{C}$, Table A-10 changed typical Reduced Performance Mode V_{DDX} Voltage to 5.0V, Table B-1
1.2	19 October 2017	<ul style="list-style-type: none"> correct max value for Input leakage current on PP1, PP3, PP5 and PP7 for $150^\circ\text{C} < T_J < 175^\circ\text{C}$ on Table A-10
1.21	24 October 2017	<ul style="list-style-type: none"> fixed minor bug in this revision history to make sure all updates are correct documented

A.1 General

This supplement contains the most accurate electrical information for the MC9S12ZVL-Family available at the time of publication.

This introduction is intended to give an overview on several common topics like power supply, current injection etc.

Table A-2. Power Supplies

Mnemonic	Nominal Voltage	Description
VSS	0V	Ground pin for 1.8V core supply voltage generated by on chip voltage regulator
VDDX	5.0 V	5V power supply output for I/O drivers generated by on chip voltage regulator if VREG5VEN is set
VDDX	3.3 V	3.3V power supply output for I/O drivers generated by on chip voltage regulator if VREG5VEN is cleared
VSSX1	0V	Ground pin for I/O drivers

Characteristics noted under conditions $5.5V \leq V_{LINSUP} \leq 18V$ unless otherwise noted ^{1 2 3} . Typical values noted reflect the approximate parameter mean at $T_A = 25^\circ C$ under nominal conditions unless otherwise noted.						
Num	Ratings	Symbol	Min	Typ	Max	Unit
9	Rising/falling edge time (min to max / max to min)	t_{rise}		13		μs
10	Over-current masking window (IRC trimmed at 1MHz) -40°C < T _J < 175C	t_{OCLIM}	31		32	μs
11	Duty cycle 3 $T_{HRec(max)} = 0.778 \times V_{LINSUP}$ $T_{HDom(max)} = 0.616 \times V_{LINSUP}$ $V_{LINSUP} = 5.5V...18V$ $t_{Bit} = 96\mu s$ $D3 = t_{Bus_rec(min)} / (2 \times t_{Bit})$	D3	0.417			
12	Duty cycle 4 $T_{HRec(min)} = 0.389 \times V_{LINSUP}$ $T_{HDom(min)} = 0.251 \times V_{LINSUP}$ $V_{LINSUP} = 5.5V...18V$ $t_{Bit} = 96\mu s$ $D4 = t_{Bus_rec(max)} / (2 \times t_{Bit})$	D4			0.590	
LIN PHYSICAL LAYER: DRIVER CHARACTERISTICS FOR FAST MODE SLEW RATE - 100KBIT/S UP TO 250KBIT/S						
13	Rising/falling edge time (min to max / max to min)	t_{rise}		0.5		μs
14	Over-current masking window (IRC trimmed at 1MHz) -40°C < T _J < 175C	t_{OCLIM}	5		6	μs

¹For $3.5V \leq V_{LINSUP} < 5V$, the LINPHY is still working but with degraded parametrics.

²For $5V \leq V_{LINSUP} < 5.5V$, characterization showed that all parameters generally stay within the indicated specification, except the duty cycles D2 and D4 which may increase and potentially go beyond their maximum limits for highly loaded buses.

³The V_{LINSUP} voltage is provided by the VLINSUP supply. This supply mapping is described in device level documentation.

O.9 0x0480-x04AF PWM0 (continued)

Address	Name		Bit 7	6	5	4	3	2	1	Bit 0
0x048A - 0x048B	RESERVED	R	0	0	0	0	0	0	0	0
		W								
0x048C	PWMCNT0	R	Bit 7	6	5	4	3	2	1	Bit 0
		W	0	0	0	0	0	0	0	0
0x048D	PWMCNT1	R	Bit 7	6	5	4	3	2	1	Bit 0
		W	0	0	0	0	0	0	0	0
0x048E	PWMCNT2	R	Bit 7	6	5	4	3	2	1	Bit 0
		W	0	0	0	0	0	0	0	0
0x048F	PWMCNT3	R	Bit 7	6	5	4	3	2	1	Bit 0
		W	0	0	0	0	0	0	0	0
0x0490	PWMCNT4	R	Bit 7	6	5	4	3	2	1	Bit 0
		W	0	0	0	0	0	0	0	0
0x0491	PWMCNT5	R	Bit 7	6	5	4	3	2	1	Bit 0
		W	0	0	0	0	0	0	0	0
0x0492	PWMCNT6	R	Bit 7	6	5	4	3	2	1	Bit 0
		W	0	0	0	0	0	0	0	0
0x0493	PWMCNT7	R	Bit 7	6	5	4	3	2	1	Bit 0
		W	0	0	0	0	0	0	0	0
0x0494	PWMPER0	R	Bit 7	6	5	4	3	2	1	Bit 0
		W								
0x0495	PWMPER1	R	Bit 7	6	5	4	3	2	1	Bit 0
		W								
0x0496	PWMPER2	R	Bit 7	6	5	4	3	2	1	Bit 0
		W								
0x0497	PWMPER3	R	Bit 7	6	5	4	3	2	1	Bit 0
		W								
0x0498	PWMPER4	R	Bit 7	6	5	4	3	2	1	Bit 0
		W								
0x0499	PWMPER5	R	Bit 7	6	5	4	3	2	1	Bit 0
		W								
0x049A	PWMPER6	R	Bit 7	6	5	4	3	2	1	Bit 0
		W								
0x049B	PWMPER7	R	Bit 7	6	5	4	3	2	1	Bit 0
		W								